

GSM22N10XF

100V N-Channel MOSFETs

Product Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode.

These devices are well suited for high efficiency fast switching applications.

Features

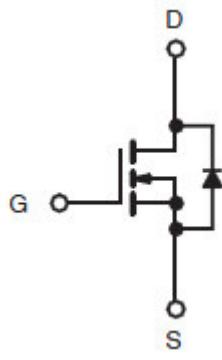
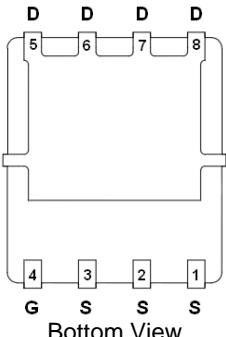
- 100V, 45A, $R_{DS(ON)} < 22m\Omega$ @ $V_{GS} = 10V$
- Improved dv/dt capability
- Fast switching
- 100% EAS guaranteed
- Green Device Available
- DFN5X6-8L package design

Applications

- Networking
- Load Switch
- LED Applications

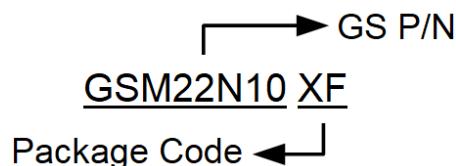
Packages & Pin Assignments

GSM22N10XF (DFN5X6-8L)	
Pin	Description
1	Source
2	Source
3	Source
4	Gate
5	Drain
6	Drain
7	Drain
8	Drain



GSM22N10XF

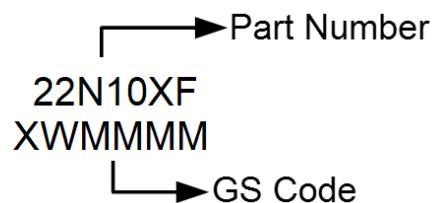
Ordering Information



GSM22N10 XF

Part Number	Package	Quantity Reel
GSM22N10XF	DFN5X6-8L	3000 PCS

Marking Information



22N10XF
XWMMMM

Absolute Maximum Ratings

T_A=25°C Unless otherwise noted

Symbol	Parameter	Typical	Unit
V _{DS}	Drain-Source Voltage	100	V
V _{GS}	Gate –Source Voltage	±20	V
I _D	Continuous Drain Current	45	A
	T _c =25°C	45	
	T _c =100°C	28	
I _{DM}	Pulsed Drain Current	150	A
EAS	Single Pulse Avalanche Energy	45	mJ
IAS	Single Pulse Avalanche Current	30	A
P _D	Power Dissipation (T _c =25°C)	96	W
T _J	Operating Junction Temperature Range	-50 to +150	°C
T _{STG}	Storage Temperature Range	-50 to +150	°C
R _{θJC}	Thermal Resistance-Junction to Case	1.2	°C/W

Electrical Characteristics

$T_A=25^\circ\text{C}$ Unless otherwise noted

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	100			V
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	1	2	3	V
I_{GSS}	Gate Leakage Current	$V_{DS}=0\text{V}, V_{GS}=\pm 20\text{V}$			± 100	nA
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=100\text{V}, V_{GS}=0\text{V}$			1	μA
I_S	Continuous Source Current	$V_G=V_D=0\text{V},$ Force Current			45	A
I_{SM}	Pulsed Source Current				90	
$R_{DS(\text{on})}$	Drain-Source On-Resistance	$V_{GS}=10\text{V}, I_D=16\text{A}$		19	22	$\text{m}\Omega$
		$V_{GS}=6\text{V}, I_D=8\text{A}$		20	24	
		$V_{GS}=4.5\text{V}, I_D=5\text{A}$		21	38	
g_{FS}	Forward Transconductance	$V_{DS}=10\text{V}, I_D=3\text{A}$		13		S
V_{SD}	Diode Forward Voltage	$V_{GS}=0\text{V}, I_S=1\text{A}$			1	V
Dynamic						
C_{iss}	Input Capacitance	$V_{DS}=25\text{V}, V_{GS}=0\text{V},$ $f=1\text{MHz}$		4708		pF
C_{oss}	Output Capacitance			326		
C_{rss}	Reverse Transfer Capacitance			247		
R_g	Gate Resistance	$V_{DS}=0\text{V}, V_{GS}=0\text{V},$ $f=1\text{MHz}$		1.6		Ω
Q_g	Total Gate Charge	$V_{DS}=80\text{V}, V_{GS}=10\text{V},$ $I_D=20\text{A}$		36		nC
Q_{gs}	Gate-Source Charge			5		
Q_{gd}	Gate-Drain Charge			10		
$t_{d(on)}$	Turn-On Time	$V_{DD}=40\text{V}, I_D=20\text{A},$ $V_{GS}=10\text{V}, R_G=3.3\Omega$		11.5		ns
t_r				29		
$t_{d(off)}$	Turn-Off Time			42		
t_f				18		

Typical Performance Characteristics

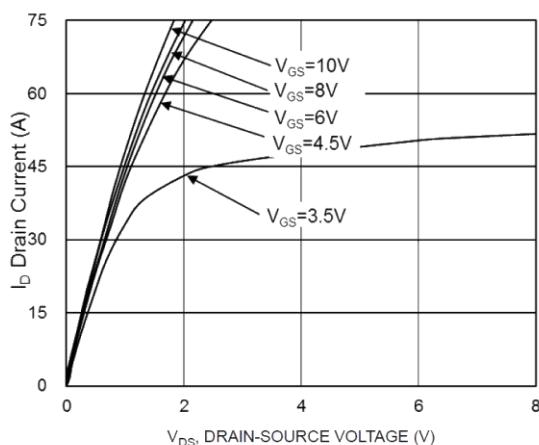


Fig. 1 Typical Output Characteristics

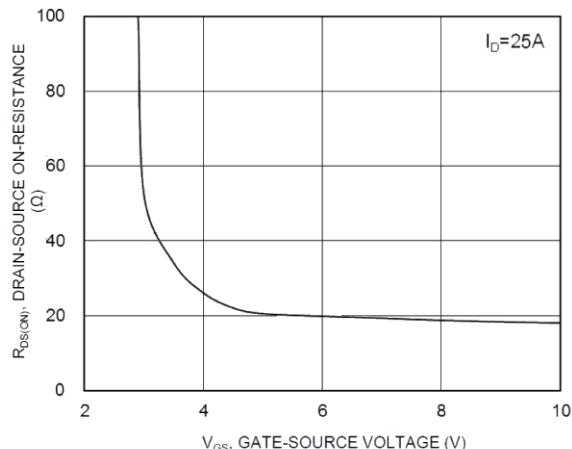


Fig. 2 Typical Transfer Characteristics

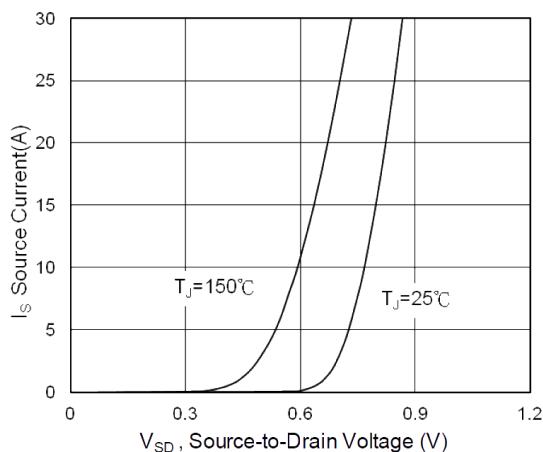


Fig. 3 Diode Forward Voltage vs. Current

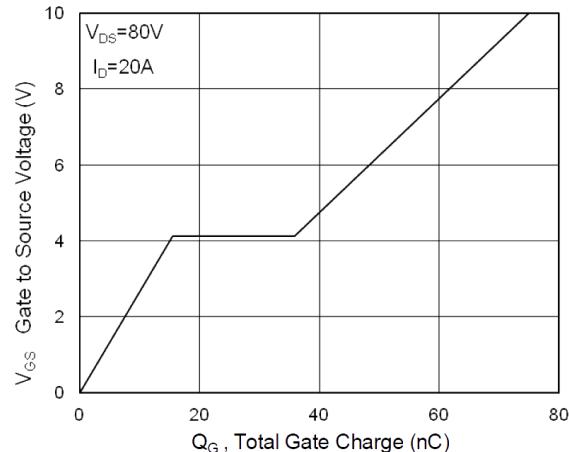


Fig. 4 Gate Charge

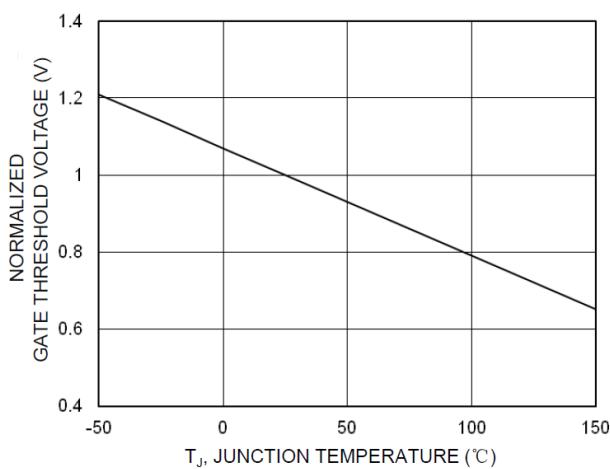


Fig. 5 Gate Threshold Variation vs. T_J

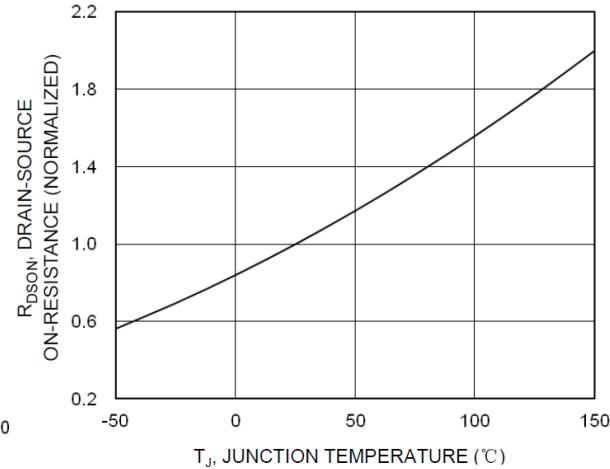


Fig. 6 On-Resistance Variation with T_J

Typical Performance Characteristics (continue)

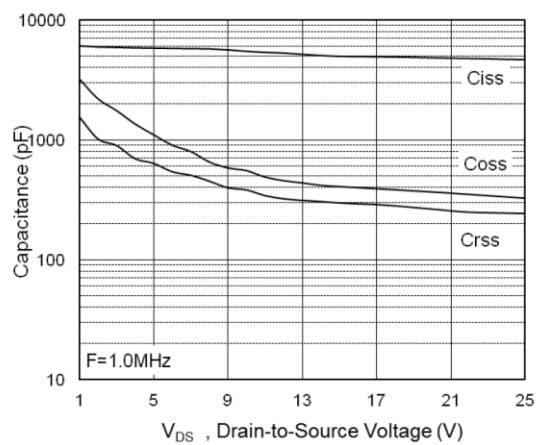
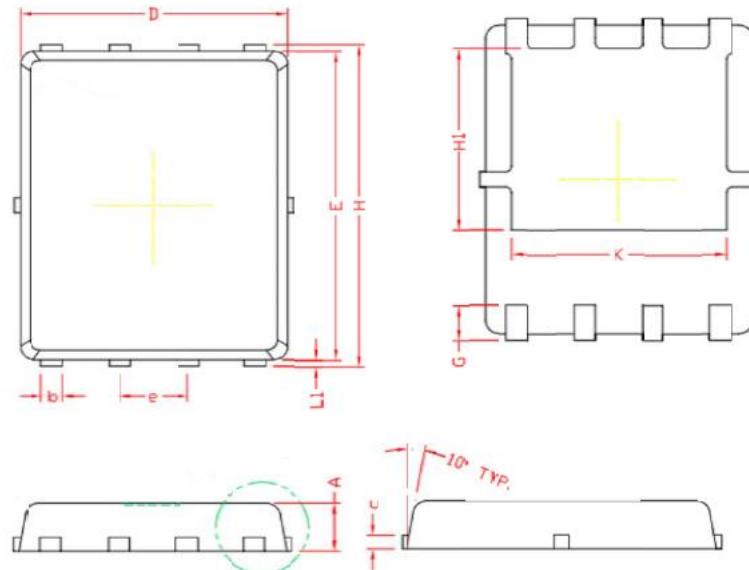


Fig. 7 Typical Capacitance

Package Dimension

DFN5X6-8L



Dimensions

SYMBOL	Millimeters		Inches	
	MIN	MAX	MIN	MAX
A	0.800	1.000	0.031	0.039
A1	0.000	0.050	0.000	0.002
b	0.250	0.490	0.014	0.019
c	0.254 REF		0.010 REF	
D	4.900	5.400	0.193	0.201
F	1.400 REF		0.055 REF	
E	5.400	5.900	0.224	0.232
e	1.270 BSC		0.050 BSC	
H	5.900	6.200	0.234	0.244
H1	3.435 REF		0.135 REF	
L1	0.100	0.250	0.012	0.009
G	0.590 REF		0.024 REF	
K	4.000 REF		0.157 REF	

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